AMENDMENTS TO THE CLAIMS

1. **(Currently amended)** A resin for a photoresist composition, having a first structural unit that comprises a hydroxyl group bonded to a carbon atom ~~at a polymer terminal~~, wherein [[a]] ~~carbon atom in an α-position to said hydroxyl group has at least one electron attractive group~~ the first structural unit comprises a $-CR^1R^2OH$ group, wherein R^1 and R^2 each represent, independently, an alkyl group, halogen atom, or halogenated alkyl group, and at least one of R^1 and R^2 is an electron attractive group selected from the group consisting of halogen atoms and halogenated alkyl groups, wherein said $-CR^1R^2OH$ group is located at a polymer terminal of said resin.

2. **(Canceled).**

3. **(Original)** A resin for a photoresist composition according to claim 1, wherein said electron attractive group is a fluorine atom or a fluorinated alkyl group.

4. **(Currently amended)** A resin for a photoresist composition according to claim 1 [[2]], wherein a proportion of the first structural ~~units (M1)~~ unit comprising said $-CR^1R^2OH$ group is at least 1 mol%, relative to a combined 100 mol% of all structural units other than said first structural ~~units (M1)~~ unit within said resin for a photoresist composition.

5. **(Currently amended)** A resin for a photoresist composition ~~having~~ according to claim 1, wherein said first structural comprises a substituent with a pKa value within a range from 6 to 12 ~~at a polymer terminal~~.

6. **(Canceled)**

7. **(Previously presented)** A resin for a photoresist composition according to claim 1, further comprising an acid dissociable, dissolution inhibiting group.

8. **(Original)** A resin for a photoresist composition according to claim 7, further comprising (a1) a structural unit derived from a (meth)acrylate ester having an acid dissociable, dissolution inhibiting group, and (a2) a structural unit derived from a (meth)acrylate ester having a lactone ring.

9. **(Original)** A resin for a photoresist composition according to claim 8, further comprising (a3) a structural unit derived from a (meth)acrylate ester having a hydroxyl group.

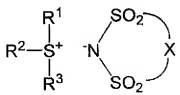
10. **(Previously presented)** A resin for a photoresist composition according to claim 1, with a weight average molecular weight of no more than 12,000.

11. **(Previously presented)** A photoresist composition, comprising a resin for a photoresist composition according to claim 1.

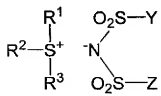
12. **(Original)** A photoresist composition according to claim 11, further comprising an acid generator as a component (B).

13. **(Original)** A photoresist composition according to claim 12, comprising as said component (B), (b-0) an onium salt that comprises a fluorinated alkylsulfonate ion as an anion.

14. **(Original)** A photoresist composition according to claim 12, comprising as said component (B), a sulfonium compound represented by either of general formulas (b-1) and (b-2) shown below:



···(b-1)



···(b-2)

wherein, X represents an alkylene group of 2 to 6 carbon atoms in which at least one hydrogen atom has been substituted with a fluorine atom; Y and Z each represent, independently, an alkyl group of 1 to 10 carbon atoms in which at least one hydrogen atom has been substituted with a fluorine atom; R^1 to R^3 each represent, independently, an aryl group or an alkyl group, and at least one of R^1 to R^3 is an aryl group.

15. **(Original)** A photoresist composition according to claim 14, further comprising as said component (B), (b-0) an onium salt that comprises a fluorinated alkylsulfonate ion as an anion.

16. **(Original)** A photoresist composition according to claim 11, further comprising a nitrogen-containing organic compound.

17. **(Original)** A method for forming a resist pattern, using a photoresist composition according to claim 11.

18. **(New)** A resin for a photoresist composition according to claim 1, wherein a proportion of the first structural units constituting said resin is 1-5 mol%, relative to a combined 100 mol% of all structural units other than said first structural units within said resin.

19. **(New)** A resin for a photoresist composition according to claim 1, wherein the first structural unit which includes the carbon atom in the α-position of said hydroxyl group having at least one electron attractive group is substantively bonded only to the polymer terminal.

20. **(New)** A resin for a photoresist composition according to claim 5, wherein a proportion of the first structural units which have the substituents with a pKa value between 6 and 12 constituting said resin is 1-5 mol% relative to a combined 100 mol% of all structural units other than said first structural units within said resin.

21. **(New)** A resin for a photoresist composition according to claim 5, wherein the substituents with a pKa value between 6 and 12 are substantively bonded only to the polymer terminal.